

UPDATED 07/25/2007

8.50-9.60 GHz 2-Watt Internally-Matched Power FET

FEATURES

- 8.50-9.60GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +33.5 dBm Output Power at 1dB Compression
- 8.0 dB Power Gain at 1dB Compression
- 30% Power Added Efficiency
- -46 dBc IM3 at PO = 22.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 8.50-9.60GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 550\text{mA}$	32.5	33.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 8.50-9.60GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 550\text{mA}$	7.0	8.0		dB
ΔG	Gain Flatness $f = 8.50-9.60GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 550\text{mA}$		±0.6	<u>+</u> 0.8	dB
PAE	Power Added Efficiency at 1dB Compression V_{DS} = 10 V, $I_{DSQ} \approx 550$ mA f = 8.50-9.60GHz		30		%
Id _{1dB}	Drain Current at 1dB Compression f = 8.50-9.60GHz		600	700	mA
IM3	Output 3rd Order Intermodulation Distortion Δf = 10 MHz 2-Tone Test; Pout = 22.5 dBm S.C.L ² V_{DS} = 10 V, $I_{DSQ} \approx 65\%$ IDSS f = 9.60GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		1000	1250	mA
V_P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 10 \text{ mA}$		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		11	12	°C/W

Notes:

- 1. Tested with 100 Ohm gate resistor.
- 2. S.C.L. = Single Carrier Level.
- 3. Overall Rth depends on case mounting.

MAXIMUM RATING AT 25 °C 1,2

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²	
Vds	Drain-Source Voltage	15	10V	
Vgs	Gate-Source Voltage	-5	-4V	
lgsf	Forward Gate Current	21.6mA	7.2mA	
lgsr	Reverse Gate Current	-3.6mA	-1.2mA	
Pin	Input Power	32.5dBm	@ 3dB Compression	
Tch	Channel Temperature	175 °C	175 °C	
Tstg	Storage Temperature	-65 to +175 °C	-65 to +175 °C	
Pt	Total Power Dissipation	12.5W	12.5W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

^{2.} Exceeding any of the above ratings may reduce MTTF below design goals.



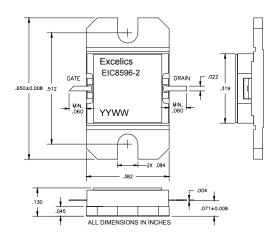
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PACKAGES OUTLINE

Dimensions in inches, Tolerance + .005 unless otherwise specified

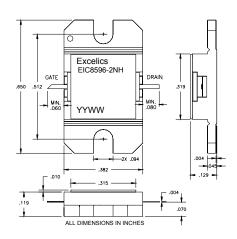
EIC8596-2 (Hermetic)





Caution! ESD sensitive device.

EIC8596-2NH (Non-Hermetic)





Caution! ESD sensitive device.

ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	IM ₃ (min) ²
EIC8596-2	Hermetic	Industrial	8.50-9.60GHz	32.5	-43
EIC8596-2NH	Non-Hermetic	Industrial	8.50-9.60GHz	32.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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